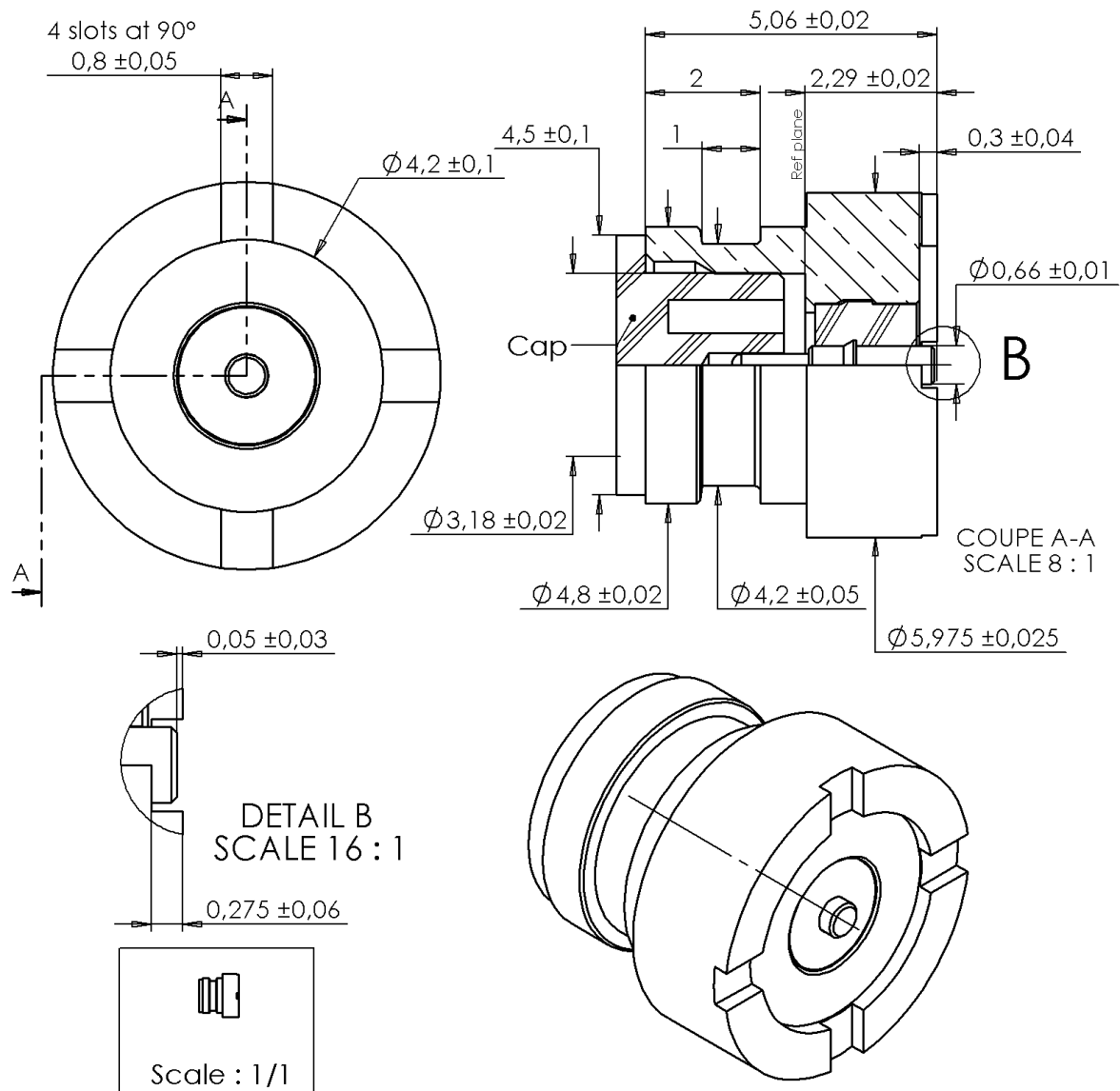


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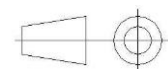
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All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)
Body	BRASS	GOLD 0.5 OVER NICKEL 2
Center contact	BERYLLIUM COPPER	GOLD 1.3 OVER NICKEL2
Outer contact		
Insulator	PTFE	
Gasket		
Others parts	PTFE	
-	-	-
-	-	-

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PACKAGING

Standard	Unit	Other
1	-	Contact us

ELECTRICAL CHARACTERISTICS

Impedance	50	Ω
Frequency	DC-18	GHz
VSWR	1.03 + 0,0150	x F(GHz) Maxi
Insertion loss	0.02+0.12	√F(GHz) dB Maxi
RF leakage	- (NA	- F(GHz)) dB Maxi
Voltage rating	335	Vrms Maxi
Dielectric withstanding voltage	500	Vrms mini
Insulation resistance	5000	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	6.8	N mini
Axial force – Opposite end	NA	N mini
Torque	NA	N.cm mini
Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm
Mating life	100	Cycles Maxi
Weight	0,7500	g Maxi

ENVIRONMENTAL

Operating temperature	-65/+165	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

SPECIFICATION

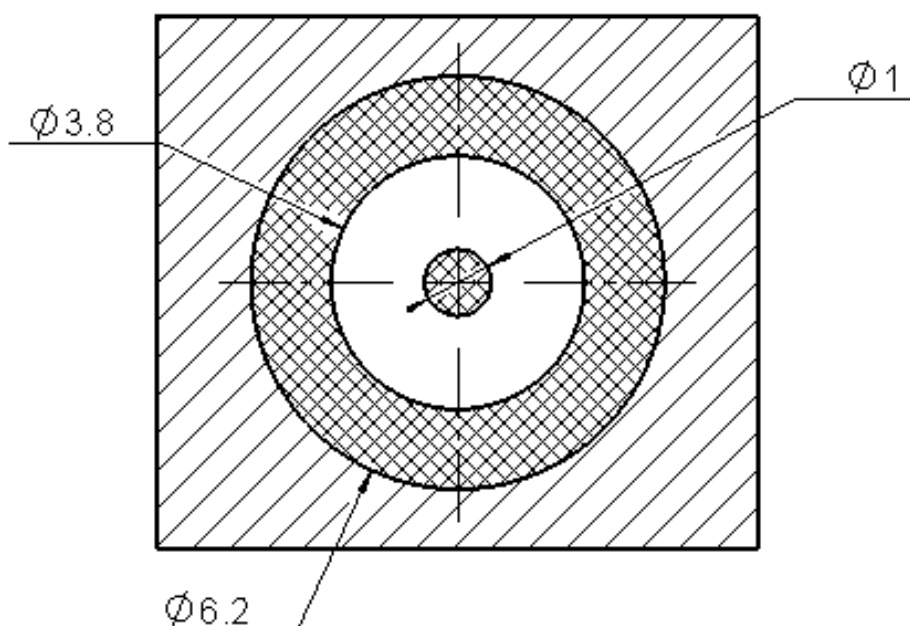
RAD-GEN-CONN 001
RAD-DET-CONN 019

OTHER CHARACTERISTICS

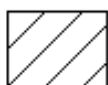
Assembly instruction:

Others:

STANDARD PAD (RADIALL RECOMMANDATION)



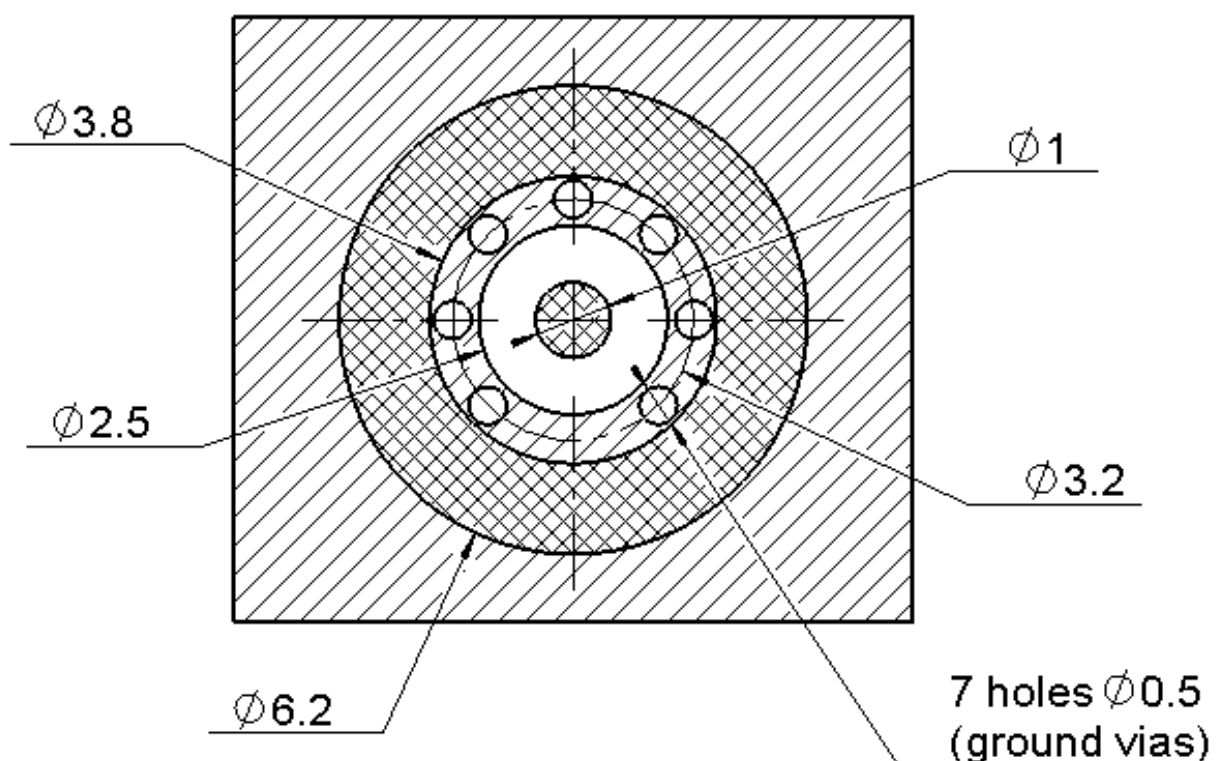
Land for solder past



Ground + varnish

- The landing pad for center contact should be linked to the stripline using a filled via.
- Upper and lower ground planes should be linked using vias.

RT DUROID 6002 (30 mils) PAD (RADIALL RECOMMANDATION)



Land for solder past



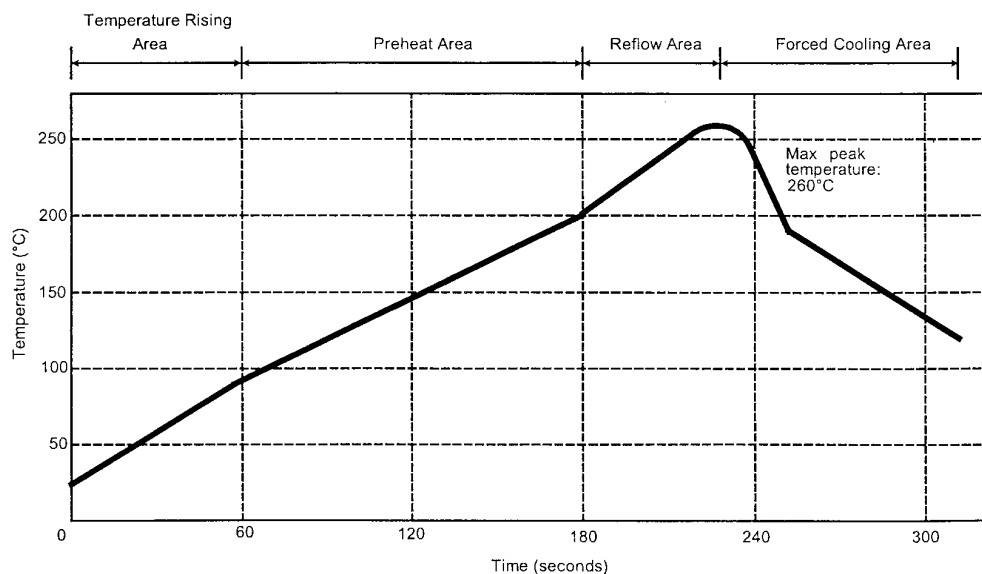
Ground + varnish

- The landing pad for center contact should be linked to the stripline using a filled via.
- Upper and lower ground planes should be linked using vias.

SOLDER PROCEDURE

1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application.
We recommend a low residue flux.
We advise a thickness of 150 µm. Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component.
Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven .Below please find, the typical profile to use.
4. The cleaning of printed circuit boards is not obliged.
5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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